LEAD FRAME, SEMICONDUCTOR PACKAGE HAVING THE SAME AND METHOD FOR MANUFACTURING THE SAME

ABSTRACT OF THE DISCLOSURE

In a lead frame with a reinforcing ring surrounding a semiconductor element which are electrically connected to leads through electrodes is integrally formed through suspending portions, reinforcing portions for reinforcing the suspending portions are provided on the suspending portiones. Upon application of a lead frame forming technique in which a laminate plate of three or more layers is used as a base, and inner leads are formed at one side while outer leads are formed by the surface layer at the other side, the lead frame is formed by forming a ring in place of outer leads, for example. A semiconductor package is formed by mounting the lead frame on a semiconductor chip.

Figure 2